

EBR #592690 ACTIVE

Header

Requestor Name :	Mahendra Kumar Rajendran	EBR Linked to :	
Requestor Email ID :	MahendraKumar.Rajendran@onsemi.com	Forecasted in another EBR :	
Contact Number :		Create Date :	2020-06-12 23:30 MST
Proxy Name :	Jake Bingham [fg6z4x], Eugene Vaynshteyn [fg6zxx], Derek Gochmour [fg6j7x], Shou-Chian Hsu [fg8rgh], Scott Brown [zbd7xx], Lillian Tsai [fg7jhp]	Submit Date :	2020-06-22 04:05 MST
CC :			
PAL2/Business Unit Group :	BA - ISG-Mobile and Consumer		
EBR Build Type :	CUSTOMER_BUILD		
Product Change Notice?	NO		
Corporate Technology Development :	No		
EBR Build Sub-Type :	No	Device ("A" PAL Codes Only) :	
Project Name :	AR0234CS Rev4.1 Mono0 CSP MP Build	Origin of the Wafer :	
Agile Project ID number :		Build :	
Purpose :	AR0234 Rev4.1 Mono0 CSP (Plain Glass) MP Build		
	Lot# 8915519.031 Total number of wafers = 2 Total Bin1 = 527 Total Bin5 = 419		
	Lot# 8924799.041 Total number of wafers =5 Total Bin1 = 1497 Total Bin5 = 868		
	Lot# 8925129.051 Total number of wafers = 3 Total Bin1 = 975 Total Bin5 = 444		
Part Release Package (PRP)/Infobook Required?	No	Authorize to Order Material :	
No Part Release Package (PRP)/Infobook Reason :	BUSINESS_DECISION		
Link/Attach Part Release Package (PRP)/Infobook :			
ISP Disclaimer Note?	No		

Change Date Reason

Reason for new submit date :	
Suggested Start Date :	

History

1			
Event Type	Event Date	Event Details	User Name
Submit To Mfg	2020-06-22 04:05 MST	EBR Submitted to Manufacturing	System User
State Change	2020-06-22 03:05 MST	EBR moved to Forecast	Lillian Tsai
Field Change	2020-06-22 03:05 MST	'productChangeNotice' changed from 'Optional' to 'No'.	Lillian Tsai
Field Change	2020-06-21 05:44 MST	EBR proxy added: Scott Brown [zbd7xx].	Mahendra Kumar Rajendran
Field Change	2020-06-21 05:44 MST	EBR proxy added: Derek Gochmour [fg6j7x].	Mahendra Kumar Rajendran
Field Change	2020-06-21 05:44 MST	EBR proxy added: Lillian Tsai [fg7jhp].	Mahendra Kumar Rajendran
Field Change	2020-06-21 05:44 MST	EBR proxy added: Shou-Chian Hsu [fg8rgh].	Mahendra Kumar Rajendran
Field Change	2020-06-21 05:44 MST	EBR proxy added: Eugene Vaynshteyn [fg6zxx].	Mahendra Kumar Rajendran
Field Change	2020-06-19 15:20 MST	'Purpose' changed from 'AR0234 Rev4.1 Mono0 CSP (Plain Glass) MP Build Lot# 8915519.031 Total number of wafers = 2 Total Bin1 = Total Bin5 = Lot# 8924799.041 Total number of wafers =5 Total Bin1 = Total Bin5 = Lot# 8925129.051 Total number of wafers = 3 Total Bin1 = Total Bin5 = ' to 'AR0234 Rev4.1 Mono0	Jake Bingham

CSP (Plain Glass) MP Build Lot# 8915519.031 Total number of wafers = 2 Total Bin1 = 527 Total Bin5 = 419 Lot# 8924799.041 Total number of wafers =5 Total Bin1 = 1497 Total Bin5 = 868 Lot# 8925129.051 Total number of wafers = 3 Total Bin1 = 975 Total Bin5 = 444 '

Field 2020-06-13 EBR proxy added: Jake Bingham [fg6z4x].  
Change 00:23 MST

Mahendra  
Kumar  
Rajendran

Area: Assembly  
Validation

Priority Level

Requested Submit Date: 2020-06-21 23:00 MST

Requested Priority: PRIORITY Requested Completion Date: 2020-07-19 23:00 MST

Priority Justification: Expedite cycle time as HOT RUN as its meant for Lead customer sampling.

Document

Assembly Site: CP3 | HUATIAN CHN FE (ART)

Cycletime Group: CSP Assembly (2 + 5 + 19)

Purchase Order Number: wait for PO

Test ENG Part Number: AR0234CS3M00SUKA0-CP-E

Total Units to be Shipped: 2999

Wafer Remnants for keep? No

Recipient Name:

No. of Lots to be Built: 3

ERP Resource Code - ASY: NA

MSL Level: 4

Assembly ENG Part Number: E-R023C09ABC-N1-KC1-WDQ

Bond Pad Size - Smallest: per BOM

Wettable Flank Required? No

Separate Lots by Wafer ID? No

Package Type: ODCSP

Target OPN (Orderable Part Number): AR0234CS3M00SUKA0-CP-E

Assembly Baseline: per BOM

Tube/Tray/Other (Packing Req): tray (no protective film)

Bond Over Active Circuit? No

Marking Requirement: \* Please follow up standard marking spec

Is this Production Marking? No

Is this Part MC status? No

Special Processing Instructions: Assemble only Bin1 dies. skip PF stage since parts are still needed to run FT at KYEC.

Lot# 8915519.031  
Total number of wafers = 2 , Wafer #2,7  
Total Bin1 = 527  
Total Bin5 = 419

Lot# 8924799.041  
Total number of wafers =5 , Wafer #2,4,5,6,7  
Total Bin1 = 1497  
Total Bin5 = 868

Lot# 8925129.051  
Total number of wafers = 3 , Wafer #5,6,8  
Total Bin1 = 975  
Total Bin5 = 444

Special Processing Instructions	EBR Lot No	MES Lot No	OPN	WDQ Part Number	Die Run	Wafer No	Marking Requirement	Starting Quantity	Equity Good Die	Remarks
xFCS:	CP3592690A									8915519.031
	CP3592690B									8924799.041
	CP3592690C									8925129.051

BOM Number:

Equivalent OPN (Orderable Part Number): AR0234CS3M00SUKA0-CP-E

Package Kit:

DFM Worksheet Available in Agile Content Container? No

Pb Free Leads? Yes

Lot Number(s): CP3592690A, CP3592690B, CP3592690C

Special Shipping Instructions: Ship all remaining Bin1 parts to KYEC for FT.

Others:

Material

+ Pending (retain at pending state when material has not arrived yet)

Incoming Carrier Tracking Number: 9196743183

Blind Assemble? No

Multi Product Wafer (Pizza Mask)? No

Reticle Map Attachment:

Is an Inkless Map Required? No

Wafer Maps Attachment: 592690\_Wafer\_Maps.zip

Electronic Maps are stored at this  
Location:

Map Files to be used:

Die Specification:

WDQ Part Number: E-R023C09ABC-N1-KC1-WDQ

Potential Die Per Wafer: 473

Wafer Technology:

Standard Wafer Process? Yes

Thickness

Composition

Passivation Layer:

Top Metal Layer:

Back Metal Layer Preparation:

Die Thickness: per BOM

Die Size: per BOM

Backgrind Information:

Incoming Lot Number(s): 8915519.031,8924799.041,8925129.051

Wafer Number(s): as Special  
Processing  
Instructions

Wafer Size: per BOM

Laser Scribe Id:

Scribe Width: per BOM

Expected Remnant Quantity: 0

Starting Quantity: 2999 Units

Engineering Traveller:

System Flow:

Inconsistent Quantity:

Lost in Shipment:

Unprocessable:

Others:

## Piece Parts

+ Pending (retain at pending state when pieceparts are not yet available)

Bonding Diagram: per BOM

Lead Frame Part Number: per BOM

Mold Compound Part Number: per BOM

Wire Bond Wire Part Number: per BOM

Clip Part Number: per BOM

Epoxy/Paste Part Number: per BOM

Wire Solder Part Number: per BOM

Solder Ball Part Number: per BOM

Package Substrate Part Number: per BOM

Lid Part Number: per BOM

## Others

In Process Review: No

In Process Review Data Required: No

Ship To:

Contact Name: TC Hsu

Email: TCHsu2@kyec.com.tw

Telephone Number: Tel:037-595666#122021/122514

Company and Address: King Yuan Electronics Co, Ltd  
No. 118, Chung-Hua Rd., Chu-Nan,  
Miao-Li 350, Taiwan  
Attention to: Sylvia Liu, TC Hsu  
Tel:037-595666 EXT#125324, EXT# 122226

Quantity:

Others:  
Processing Reports:

## Area Attachments

File Attachments:

## Manufacturing Dates

## Validation Dates

Validator Name:

Forecasted Start Date: 2020-06-23 23:00 MST

Baseline Start Date: 2020-06-24 04:05 MST

Expected Start Date: 2020-06-24 04:05 MST

Start Date:

Forecasted End Date: 2020-06-25 23:00 MST

Baseline End Date: 2020-06-26 04:05 MST

Expected End Date: 2020-06-26 04:05 MST

End Date:

## Queue Dates

Planner Name:

Forecasted Start Date: 2020-06-25 23:00 MST

Baseline Start Date: 2020-06-26 04:05 MST

Expected Start Date: 2020-06-26 04:05 MST

Start Date:

Firm Start Date:

Forecasted End Date: 2020-06-30 23:00 MST

Baseline End Date: 2020-07-01 04:05 MST

Expected End Date: 2020-07-01 04:05 MST

End Date:

## Processing Dates

Mfg Representative:

Forecasted Start Date: 2020-06-30 23:00 MST

Baseline Start Date: 2020-07-01 04:05 MST

Expected Start Date: 2020-07-01 04:05 MST

Start Date:

Forecasted End Date: 2020-07-19 23:00 MST

Baseline End Date: 2020-07-20 04:05 MST

Expected End Date: 2020-07-20 04:05 MST

End Date:

Reason for Delay:

## Communication

Message History:

New Message:

## Area History

Event Type	Event Date	State Name	Event Details	User Name
State Change	2020-06-22 04:05 MST	Validation	Area moved from 'Committed Forecast Accepted' to 'Validation'.	System User
State Change	2020-06-22 03:15 MST	Committed Forecast Accepted	Area moved from 'Forecast Validation' to 'Committed Forecast Accepted'.	Lillian Tsai
State Change	2020-06-22 03:15 MST	Forecast Validation	Area moved from 'Forecast' to 'Forecast Validation'.	Lillian Tsai
Field Change	2020-06-22 03:15 MST	Forecast	'requestedCompletionDate' set to '2020-07-20 CST'.	Lillian Tsai
State Change	2020-06-22 03:05 MST	Forecast	Area moved from 'Draft' to 'Forecast'.	Lillian Tsai
Field Change	2020-06-22 03:05 MST	Draft	'poNumber' set to 'wait for PO'.	Lillian Tsai
Field Change	2020-06-22 03:05 MST	Draft	'requestedSubmitDate' set to '2020-06-22 CST'.	Lillian Tsai
Field Change	2020-06-21 05:41 MST	Draft	'totUnitShipped' set to '2999'.	Mahendra Kumar Rajendran
Field Change	2020-06-21 05:41 MST	Draft	'incomingCarrierName' set to 'DHL'.	Mahendra Kumar Rajendran
Field Change	2020-06-21 05:41 MST	Draft	'startingQty' set to '2999'.	Mahendra Kumar Rajendran
Field Change	2020-06-19 15:26 MST	Draft	'incomingCarrierTrackingNumber' set to '9196743183'.	Jake Bingham
Field Change	2020-06-19 15:20 MST	Draft	'spclProcessingInstruction' changed from 'Assemble only Bin1 dies. skip PF stage since parts are still needed to run FT at KYEC. Lot# 8915519.031 Total number of wafers = 2 , Wafer # Total Bin1 = Total Bin5 = Lot# 8924799.041 Total number of wafers =5 , Wafer # Total Bin1 = Total Bin5 = Lot#	Jake Bingham

			8925129.051 Total number of wafers = 3 , Wafer # Total Bin1 = Total Bin5 = ' to 'Assemble only Bin1 dies. skip PF stage since parts are still needed to run FT at KYEC. Lot# 8915519.031 Total number of wafers = 2 , Wafer #2.7 Total Bin1 = 527 Total Bin5 = 419 Lot# 8924799.041 Total number of wafers =5 , Wafer #2,4,5,6,7 Total Bin1 = 1497 Total Bin5 = 868 Lot# 8925129.051 Total number of wafers = 3 , Wafer #5,6,8 Total Bin1 = 975 Total Bin5 = 444 '.		
Field Change	2020-06-13 00:18 MST	Draft	'quantity' set from '1498' to " (for #1 contact name 'TC Hsu').		Mahendra Kumar Rajendran
Field Change	2020-06-12 23:41 MST	Draft	'incomingLotNumber' changed from '8849439,8849209,8883559' to '8915519.031,8924799.041,8925129.051' (for #1 WDQ part number 'E-R023C09ABC-N1-KC1-WDQ').		Mahendra Kumar Rajendran
Field Change	2020-06-12 23:37 MST	Draft	'spclProcessingInstruction' changed from 'Assemble only Bin1 dies. skip PF stage since parts are still needed to run FT at KYEC. Lot# 8849439 Total number of wafers = 2 , Wafer # 1,20 Total Bin1 = Total Bin5 = Lot# 8849209 Total number of wafers = 2 , Wafer # 13,23 Total Bin1 = Total Bin5 = Lot# 8883559 Total number of wafers = 2 , Wafer # 14,24 Total Bin1 = Total Bin5 = ' to 'Assemble only Bin1 dies. skip PF stage since parts are still needed to run FT at KYEC. Lot# 8915519.031 Total number of wafers = 2 , Wafer # Total Bin1 = Total Bin5 = Lot# 8924799.041 Total number of wafers =5 , Wafer # Total Bin1 = Total Bin5 = Lot# 8925129.051 Total number of wafers = 3 , Wafer # Total Bin1 = Total Bin5 = '.		Mahendra Kumar Rajendran
Field Change	2020-06-12 23:37 MST	Draft	'totUnitShipped' set from '1744' to ".		Mahendra Kumar Rajendran
Field Change	2020-06-12 23:37 MST	Draft	'startingQty' set from '1744' to ".		Mahendra Kumar Rajendran
Field Change	2020-06-12 23:31 MST	Draft	'lotNumber' set to 'CP3592690A, CP3592690B, CP3592690C'.		Mahendra Kumar Rajendran